

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<i>In re</i> Application of:	Byung Tai Do, et al.	:	Confirmation No.:	8877
Serial No.:	10/825,910	:	Art Unit:	2818
Filed:	4/16/2004	:	Examiner:	Tu Tu V Ho
For:	THERMALLY ENHANCED STACKED DIE PACKAGE AND FABRICATION METHOD	:		

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**AMENDMENT AND RESPONSE AFTER FINAL REJECTION
UNDER 37 C.F.R. §1.116**

Sir/Madam:

The following Amendment and Remarks are submitted under 37 C.F.R. §1.116 in response to the Final Office Action mailed August 21, 2006, following the amendment format set forth under 37 CFR §1.121. After this introductory section, there are Amendments to the Claims and then Remarks, each starting on a separate page.

Amendments to the Claims consist of amendments for claims 6 and 16, which are incorporated in a complete listing of the claims.

Reconsideration of the rejections is respectfully requested.